SLVS602-MARCH 2006

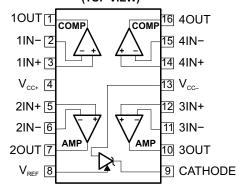
FEATURES

- OPERATIONAL AMPLIFIERS
 - Low Supply Current...200 μ A/A
 - Medium Speed...2.1 MHz
 - Low-Level Output Voltage Close to V_{CC-} ...0.1 V Typ ($R_L = 10 \text{ k}\Omega$)
 - Input Common-Mode Voltage Range Includes Ground
- COMPARATORS
 - Low Supply Current...200 μA/A (V_{CC} = 5 V)
 - Input Common-Mode Voltage Range Includes Ground
 - Low Output Saturation Voltage...
 Typically 250 mV (I_{sink} = 4 mA)
- VOLTAGE REFERENCE
 - Adjustable Output Voltage...V_{REF} to 36 V
 - Sink Current Capability...1 mA to 100 mA
 - 0.4% (A Grade) and 1% (Standard Grade)
 Precision
 - Latch-Up Immunity

APPLICATIONS

- Switch-Mode Power Supplies
- Battery Chargers
- Voltage and Current Sensing
- Power-Good, Overvoltage, Undervoltage, Overcurrent Detection
- Window Comparators
- Alarms, Detectors, and Sensors

D (SOIC) OR PW (TSSOP) PACKAGE (TOP VIEW)



DESCRIPTION/ORDERING INFORMATION

The TSM102 and TMS102A combine the building blocks of a dual operational amplifier, a dual comparator, and a precision voltage reference, all of which often are used to implement a wide variety of power-management functions, including overcurrent detection, undervoltage/overvoltage detection, power-good detection, window comparators, error amplifiers, etc. Additional applications include alarm and detector/sensor applications.

The TSM102A offers a tight V_{REF} tolerance of 0.4% at 25°C. The TSM102 and TSM102A are characterized for operation from -40°C to 85°C.

ORDERING INFORMATION

T _A	MAX V _{REF} TOLERANCE (25°C)	PACKAGE ⁽¹⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING
		SOIC - D	Tube of 75	TSM102AID	TSM102AI
	A grade:	30IC – D	Reel of 2500	TSM102AIDR	TSWIUZAI
	0.4% precision	TSSOP – PW	Tube of 90	TSM102AIPW	SN102AI
–40°C to 85°C		1330P – PW	Reel of 2000	TSM102AIPWR	SINTUZAI
-40 C to 65 C		0010 5	Tube of 75	TSM102ID	TCM400L
	Standard grade:	SOIC - D	Reel of 2500	TSM102IDR	TSM102I
	1% precision	TSSOP – PW	Tube of 90	TSM102IPW	SN102I
		1330F - FW	Reel of 2000	TSM102IPWR	SIN1021

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

SLVS602-MARCH 2006



Absolute Maximum Ratings⁽¹⁾

over free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{CC}	Supply voltage			36	V
V_{ID}	Input differential voltage			36	V
VI	Input voltage range		-0.3	36	V
I _{KA}	Voltage reference cathode current			100	mA
0	Package thermal impedance (2)(3)	D package		73	°C/W
θ_{JA}	Package thermal impedance ⁽²⁾⁽³⁾	PW package		108	°C/VV
T_{J}	Maximum junction temperature			150	°C
T _{stg}	Storage temperature range		-65	150	°C

Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

Recommended Operating Conditions

		MIN	MAX	UNIT
V _{CC+} - V _{CC-}	Supply voltage	3	30	V
V _{ID}	Comparator differential input voltage		V _{CC+} – V _{CC}	V
V _{KA}	Cathode-to-anode voltage	V _{REF}	36	V
I _K	Reference cathode current	1	100	mA
T _A	Operating free-air temperature	-40	85	°C

Total Device Electrical Characteristics

	PARAMETER	TEST CONDITIONS	TA	MIN	TYP	MAX	UNIT
	Total supply current,	V - 5 V V - 0 V No load	25°C		0.8	1.5	m ^
ıc	excluding reference cathode current	$V_{CC+} = 5 \text{ V}, V_{CC-} = 0 \text{ V}, \text{ No load}$	Full range			2	mA

Maximum power dissipation is a function of $T_J(max)$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) - T_A)/\theta_{JA}$. Selecting the maximum of 150°C can affect reliability. (3) The package thermal impedance is calculated in accordance with JESD 51-7.



SLVS602-MARCH 2006

Operational Amplifier Electrical Characteristics

 $\rm V_{CC+}$ = 5 V, $\rm V_{CC-}$ = GND, R1 connected to $\rm V_{CC}/2$ (unless otherwise noted)

	PARAMETER	TEST CONDITION	IS	T _A	MIN	TYP	MAX	UNIT
V	lanut effect veltere			25°C		1	4.5	\/
V _{IO}	Input offset voltage			Full range			6.5	mV
αV_{IO}	Input offset voltage drift			25°C		10		μV/°C
	Input offset current			25°C		5	20	nA
I _{IO}	input onset current			Full range			40	IIA
	Input bigg gurrent			25°C		20	100	nA
I _{IB}	Input bias current			Full range			200	IIA
^	Large-signal voltage gain	$V_{CC+} = 30 \text{ V}, R1 = 10 \text{ k}\Omega,$		25°C	50	100		V/mV
A_{VD}	Large-Signal voltage gain			Full range	25			V/IIIV
k _{SVR}	Supply-voltage rejection ratio	$V_{CC+} = 5 \text{ V to } 30 \text{ V}$		25°C	80	100		dB
V	Input common-mode voltage			25°C	V_{CC-}		V _{CC+} – 1.8	V
V _{ICM}	input common-mode voltage			Full range	V _{CC} -		V _{CC+} – 2.2	V
CMRR	Common-mode rejection ratio	$V_{CC+} = 30 \text{ V},$ $V_{ICM} = 0 \text{ V to } V_{CC+} - 1.8 \text{ V}$		25°C	70	90		dB
	Short-circuit current	$V_{ID} = \pm 1 \text{ V}, V_{O} = 2.5 \text{ V}$	Source	25°C	3	6		mA
I _{SC}	Short-circuit current	$v_{\text{ID}} = \pm i v, v_{\text{O}} = 2.5 v$	Sink	25 C	3	6		ША
V	High lovel output voltage	$V_{CC+} = 30 \text{ V}, R_1 = 10 \text{ k}\Omega$		25°C	27	28		V
V _{OH}	High-level output voltage	$V_{CC+} = 30 \text{ V}, \text{ KL} = 10 \text{ K}22$		Full range	26			V
V	Low-level output voltage	$R_1 = 10 \text{ k}\Omega$		25°C		130	170	mV
V _{OL}	Low-level output voltage	$R_L = 10 \text{ ksz}$		Full range			200	IIIV
SR	Slew rate	$V_{CC} = \pm 15 \text{ V}, C_L = 100 \text{ pF}, V_I = \pm 10 \text{ V}, R_L = 10 \text{ k}\Omega$		25°C	1.3	2		V/μs
GBW	Gain bandwidth product	$R_L = 10 \text{ k}\Omega, C_L = 100 \text{ pF, f}$	= 100 kHz	25°C	1.4	2.1		MHz
Φт	Phase margin	$R_L = 10 \text{ k}\Omega, C_L = 100 \text{ pF}$		25°C		45		0
THD	Total harmonic distortion			25°C		0.01		%
V _n	Equivalent input noise voltage	f = 1 kHz		25°C		19		nV/√ Hz

SLVS602-MARCH 2006



Comparator Electrical Characteristics

 $V_{CC+} = 5 \text{ V}, V_{CC-} = \text{GND} \text{ (unless otherwise noted)}$

	PARAMETER	TEST CONDITIONS	T _A	MIN	TYP	MAX	UNIT	
V	Input offeet voltage		25°C			5	mV	
V _{IO}	Input offset voltage		Full range			9	mv	
V _{ID}	Comparator differential input voltage		Full range			V _{CC+}	V	
1	Input offset current		25°C			50	nA	
I _{IO}	input onset current		Full range			150	IIA	
	Input high ourrent		25°C			250	nA	
I _{IB}	Input bias current		Full range			400	ПА	
	High lovel output ourrent	V - 1 V V - V - 20 V	25°C		0.1		nA	
I _{OH}	High-level output current	$V_{ID} = 1 \text{ V}, V_{CC} = V_{O} = 30 \text{ V}$	Full range			1	μΑ	
V	Low lovel output voltage	V - 1 V I - 4 mA	25°C		250	400	mV	
V _{OL}	Low-level output voltage	$V_{ID} = -1 V$, $I_{sink} = 4 \text{ mA}$	Full range			700	IIIV	
A _{VD}	Large-signal voltage gain	$V_{CC+} = 15 \text{ V}, R1 = 15 \text{ k}\Omega, V_{O} = 1 \text{ V to } 11 \text{ V}$	25°C		200		V/mV	
I _{sink}	Output sink current	$V_{O} = 1.5 \text{ V}, V_{ID} = -1 \text{ V}$	25°C	6	16		mA	
V	Input common-mode		25°C	0		V _{CC+} – 1.5	V	
V _{ICM}	voltage range		Full range	0		V _{CC+} – 2	V	
t _{RESP}	Response time ⁽¹⁾	R1 = 5.1 k Ω to V _{CC+} , V _{REF} = 1.4 V	25°C		1.3		μs	
t _{RESP,large}	Large-signal response time	R1 = 5.1 k Ω to V _{CC+} , V _{REF} = 1.4 V, V _I = TTL	25°C		300		ns	

⁽¹⁾ The response-time specification is for 100-mV input step with 5-mV overdrive. For larger overdrive signals, 300 ns can be obtained.



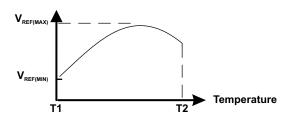
SLVS602-MARCH 2006

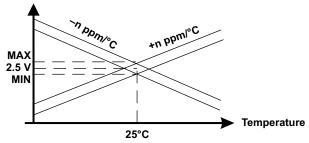
Voltage-Reference Electrical Characteristics

	PARAMETER		TEST CONDITIONS	T _A	MIN	TYP	MAX	UNIT
V	Reference voltage ⁽¹⁾	TSM102	$V_{KA} = V_{REF}$, $I_K = 10$ mA,	25°C	2.475	2.5	2.525	V
V _{REF}	Reference voltage	TSM102A	See Figure 1	25°C	2.49	2.5	2.51	V
ΔV_{REF}			$V_{KA} = V_{REF}$, $I_K = 10$ mA, See Figure 1	Full range		7	30	mV
$\frac{V_{\text{REF}}}{T}$	Average temperature coefficient of reference input voltage (2)		$V_{KA} = V_{REF}$, $I_K = 10 \text{ mA}$	Full range		±22	±100	ppm/°C
$\frac{V_{REF}}{V_{KA}}$	Ratio of change in reference voltage to change in cathode voltage		$V_{KA} = 3 \text{ V to } 36 \text{ V}, I_{K} = 10 \text{ mA},$ See Figure 2	25°C		-1.1	-2	mV/V
	Deference input current		$I_{K} = 10 \text{ mA}, R1 = 10 \text{ k}\Omega, R2 = \infty,$	25°C		1.5	2.5	^
I _{REF}	Reference input current		See Figure 2	Full range			3	μΑ
ΔI_{REF}	Reference input current deviation over temperature range		I_K = 10 mA, R1 = 10 k Ω , R2 = ∞ , See Figure 2	Full range	Full range (1	μΑ
I _{min}	Minimum cathode current for regulation		V _{KA} = V _{REF} , See Figure 1	25°C		0.5	1	mA
$I_{K,OFF}$	Off-state cathode current		See Figure 3	25°C		180	500	nA

(1) ΔV_{REF} is defined as the difference between the maximum and minimum values obtained over the full temperature range. ΔV_{REF} = V_{REF(MAX)} - V_{REF(MIN)}
 (2) The temperature coefficient is defined as the slopes (positive and negative) of the voltage vs temperature limits within which the

reference voltage is specified.







PARAMETER MEASUREMENT INFORMATION

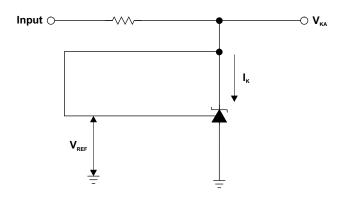


Figure 1. Test Circuit for $V_{KA} = V_{REF}$

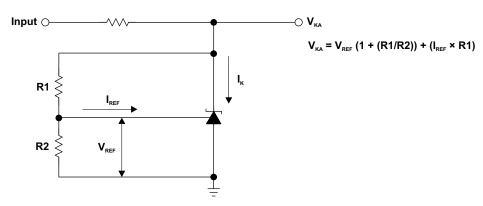


Figure 2. Test Circuit for $V_{KA} > V_{REF}$

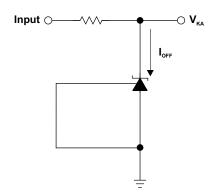
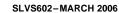


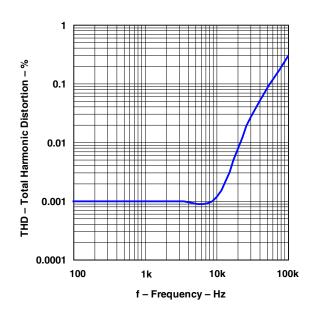
Figure 3. Test Circuit for I_{OFF}





TYPICAL CHARACTERISTICS

AMPLIFIER TOTAL HARMONIC DISTORTION VS FREQUENCY



AMPLIFIER NOISE VOLTAGE VS FREQUENCY

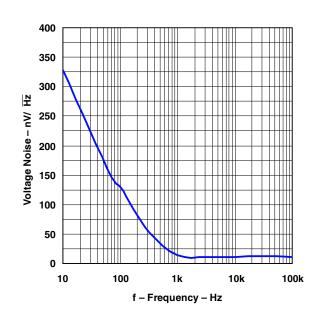
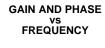


Figure 4.



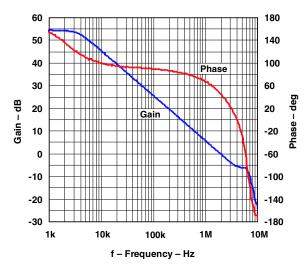


Figure 5.



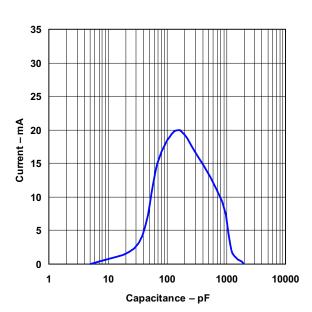
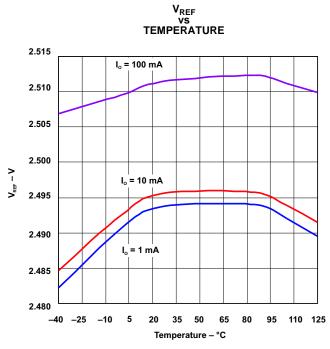


Figure 6.

Figure 7.



TYPICAL CHARACTERISTICS (continued)



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PACKAGING INFORMATION

Orderable part number	Status	Material type	Package Pins	Package qty Carrier	RoHS	Lead finish/	MSL rating/	Op temp (°C)	Part marking
	(1)	(2)			(3)	Ball material	Peak reflow		(6)
						(4)	(5)		
TSM102AIDR	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TSM102AI
TSM102AIDR.A	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TSM102AI
TSM102AIPW	Active	Production	TSSOP (PW) 16	90 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	SN102AI
TSM102AIPW.A	Active	Production	TSSOP (PW) 16	90 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	SN102AI
TSM102AIPWR	Active	Production	TSSOP (PW) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	SN102AI
TSM102AIPWR.A	Active	Production	TSSOP (PW) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	SN102AI
TSM102ID	Active	Production	SOIC (D) 16	40 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TSM102I
TSM102ID.A	Active	Production	SOIC (D) 16	40 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TSM102I
TSM102IDR	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TSM102I
TSM102IDR.A	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TSM102I
TSM102IPWR	Active	Production	TSSOP (PW) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	SN102I
TSM102IPWR.A	Active	Production	TSSOP (PW) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	SN102I

⁽¹⁾ Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.



PACKAGE OPTION ADDENDUM

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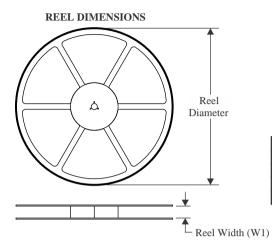
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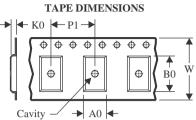
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

PACKAGE MATERIALS INFORMATION

www.ti.com 25-Jul-2025

TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

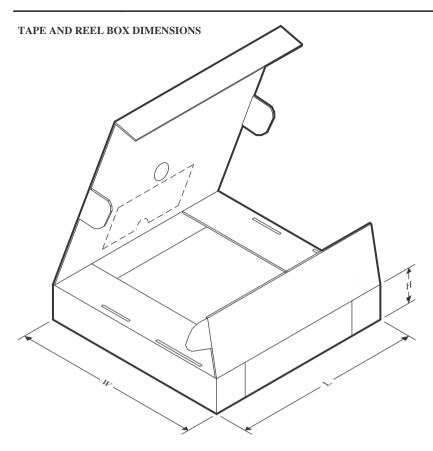
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TSM102AIDR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
TSM102AIPWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
TSM102IDR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
TSM102IPWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

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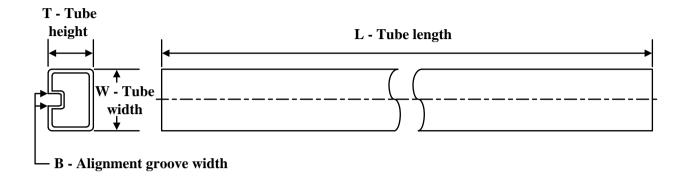
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TSM102AIDR	SOIC	D	16	2500	353.0	353.0	32.0
TSM102AIPWR	TSSOP	PW	16	2000	353.0	353.0	32.0
TSM102IDR	SOIC	D	16	2500	353.0	353.0	32.0
TSM102IPWR	TSSOP	PW	16	2000	353.0	353.0	32.0

PACKAGE MATERIALS INFORMATION

www.ti.com 25-Jul-2025

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
TSM102AIPW	PW	TSSOP	16	90	530	10.2	3600	3.5
TSM102AIPW.A	PW	TSSOP	16	90	530	10.2	3600	3.5
TSM102ID	D	SOIC	16	40	506.6	8	3940	4.32
TSM102ID.A	D	SOIC	16	40	506.6	8	3940	4.32

D (R-PDS0-G16)

PLASTIC SMALL OUTLINE



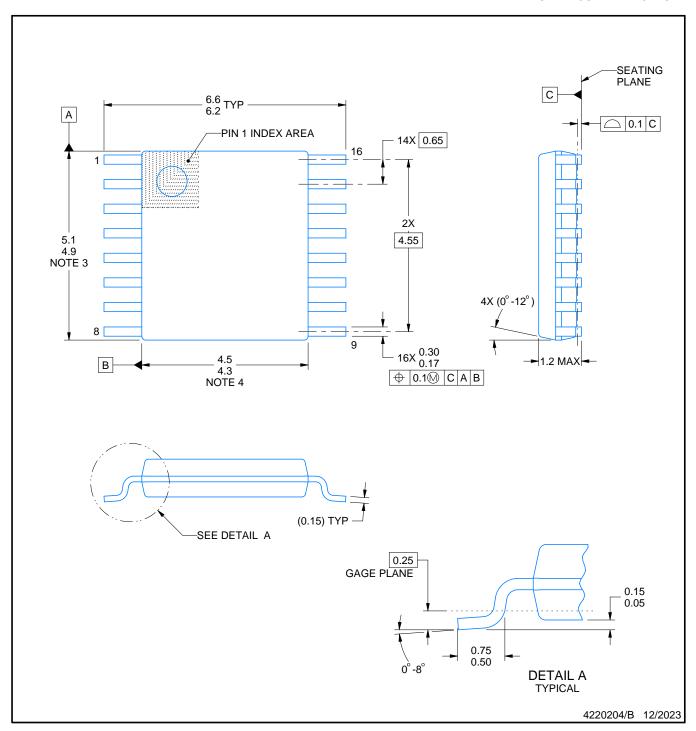
NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.





SMALL OUTLINE PACKAGE



NOTES:

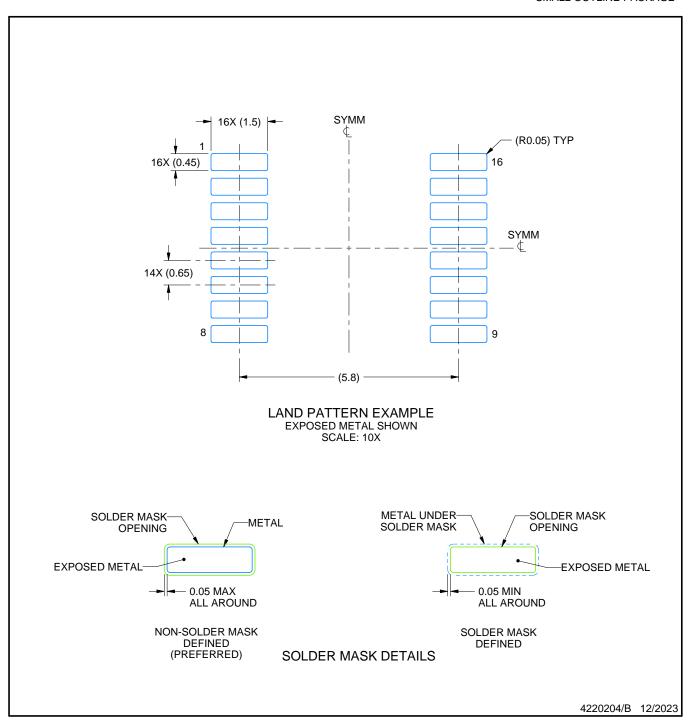
- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE

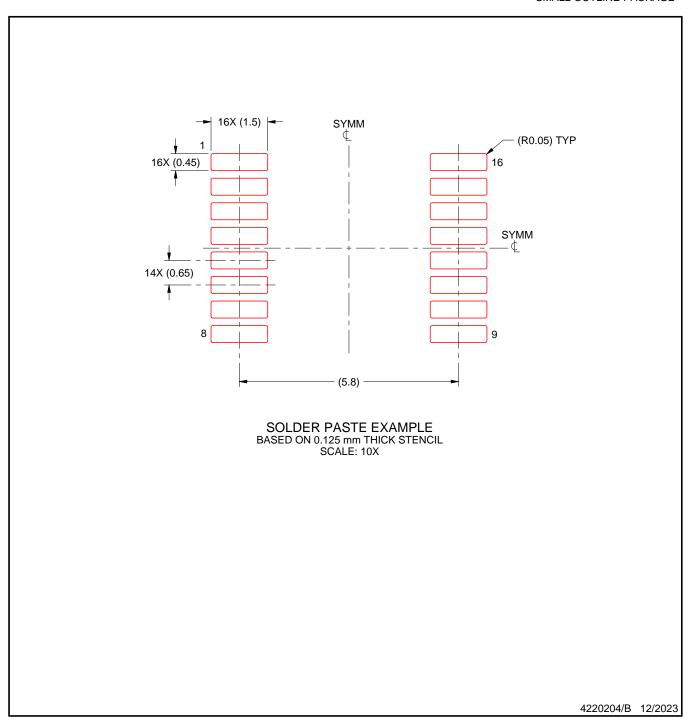


NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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